ON Semiconductor

GENERAL ANNOUNCEMENT

29 Jan 2009

SUBJECT: ON Semiconductor General Announcement #GA16200

TITLE: Conversion of Gold wire to Copper wire in ON Semiconductor's Assembly Facilities

EFFECTIVE DATE: 29 Jan 2009

AFFECTED PRODUCT DIVISION: Analog Power Management~Standard Components~Integrated Power Devices

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact Your Local ON Semiconductor Sales Representative or mark.wasilewski@onsemi.com>

DESCRIPTION AND PURPOSE:

On Semiconductor is notifying customers of the intent to convert to Copper Wire bond technology on most of the semiconductor packages. This would be implemented across all product types and packages over the next 12-18 months. There will be no plan to change any other package materials other that the wire in association with this notice. If there are any exceptions to this, it will be specified in the Final Product Change Notice that will be issued prior to production implementation for each product family. This General Announcement will serve as a replacement to the Initial Process Change Notice typically issued in an attempt to minimize the number of total customer notices received.

Prior to the FPCN's being issued, full device and temperature characterizations will be completed on all qualification vehicles in order to insure device functionalities and electrical specifications are met. There will be multiple Final PCN's issued as the lines and families are converted over the following many months. The Final Product Change Notice's will be issued at least 90 days prior to devices being converted to Copper Wire.

Reliability testing will also be completed prior to release of the FPCN's. Reliability qualification testing will include:

Test: High Temperature Reverse Bias (HTRB)
Conditions: V= 80% rating, Ta=150'C, 1008 Hrs

Test: High Temperature Gate Bias (HTGB)
Conditions: V= 100%, Ta=150'C, 1008 Hrs

Test: High Temperature Operating Life (HTOL)
Conditions: V= 100% Bias. Ta=125'C, 504-Hrs.

Test: Intermittent Operating Life (IOL-PC)
Conditions: Ta=+25'C, delta Tj=100'C, 2-min on/off, 7.5K-cycles

Test: Temperature Cycling (TC-PC)
Conditions: Ta=-65'C/+150'C, Air-to-Air, Dwell >=10-min, 1000-cy

Test: Highly Accelerated Stress Test (HAST-PC)
Conditions: Ta=130'C, RH=85%, P=18.8psig, 96-Hrs

There will be no change to the form, fit, and function of the devices. Device parameters will continue to meet all Data Book specifications, and reliability will continue to meet or exceed ON Semiconductors standards.

AFFECTED DEVICE LIST

This is a General Announcement. General Announcements do not contain a specific list of affected devices. GPCN uses these announcements when all or no devices are affected.